

JEDEC STANDARD

DDR5 UDIMM Raw Card Annex B

JESD308-U0-RCB Version 1.0

JULY 2022

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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DDR5 UDIMM RAW CARD ANNEX B

From JEDEC Board Ballet JCB-22-16, formulated under the cognizance of the JC-45.3 Subcommittee on Unbuffered DRAM Modules, item 2265.13A.

1 Scope

This annex JESD308-U0-RCB, DDR5 Unbuffered Dual Inline Memory Module (UDIMM) Raw Card B Annex defines the design detail of x8, 2 Package Ranks DDR5 UDIMM. The common feature of DDR5 UDIMM such as the connector pinout can be found in the JESD308, DDR5 Unbuffered Dual Inline Memory Module (UDIMM) Common Standard.

2 DDR5 Unbuffered DIMM Design File

Table 1 — DDR5 UDIMM Design File

Raw Card	Applicable Design File	Applicable BOM
B0	PC5_UDIMM_RC_B0_R100_20210720.brd	PC5_UDIMM_RC_B0_R100_20210720_BOM.xlsx
NOTE	"Reference" design file updates will be released as needed. This DIMM specification will reflect the most recent design files, but may also be updated to reflect clarifications to the specification only. In these cases the design files will not be updated.	

3 Module Configuration

Table 2 — Module Configuration

SDRAM					DIMM										
Die Density	Die Organization	Pack-age Type	# of Logical Ranks ¹ per PKG. Rank		# of PKG. Rank 1,2 per DIMM	# of Logical Ranks ¹ per DIMM		# of SDRAM die per DIMM		Capacity per DIMM (GB)		DIMM Organization		# of Address bits row/col	MO-329 variation
			Min.	Max.			Min.	Max.	Min.	Max.	Min.	Max.	Min.		
16Gb	2G x 8	SDP	-	-	2	2	2	16	16	32	32	4Gx64	4Gx64	16/10	ABxB
24Gb	3G x 8	SDP	-	-	2	2	2	16	16	48	48	6Gx64	6Gx64	17/10	ABxB
32Gb	4G x 8	SDP	-	-	2	2	2	16	16	64	64	8Gx64	8Gx64	17/10	ABxB
NOTE 1 When populated with single die package (SDP), package ranks per DIMM = 2															

4 SDRAM Configuration

Table 3 — SDRAM Configuration

Raw Card	Supported DRAM Outline (Width x Length) max. (mm)	Number of Bank Groups/ Banks in a Group	SDRAM Package Type	Package Type	MO-210 Variation
B0	10.1 x 11.1	8/4	82 Ball FBGA	SDP	AN
NOTE 1 SDP is a single die per package. NOTE 2 MO-210 variation AL is a 78-ball FBGA and is acceptable for placement.					

5 Supported Speeds

Table 4 — Supported Speeds

Raw Card	Speed	PC5-4400	PC5-4800	PC5-5600	PC5-6400	Notes
B0	DDR5	Y	Y			1, 2
NOTE 1 X reflects speed grades approved from previous ballots. NOTE 2 Y denotes speed grades newly supported.						

6 Design Deviations

Table 5 — Design Deviations

None.
